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## Embedded OEM

### DRAM

#### DDR3

- DDR2
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Flash

SSD

ADD2

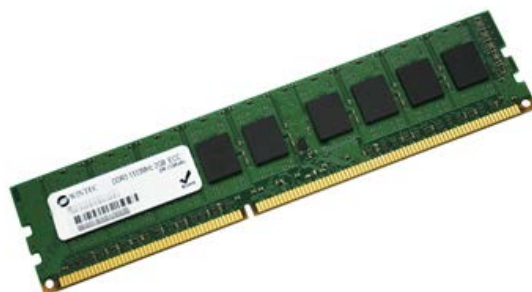
Modems

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# DRAM DDR3

## UDIMM

RDIMM	UDIMM	SODIMM	mini DIMM
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DDR3 is the current mainstream dram technology standardized by JEDEC, bringing further improvements in power consumption and increased bandwidth over DDR2. Available in power supply voltages of 1.5V (DDR3) and 1.35V (DDR3L) and with transfer data rates from 800Mb/s to 1.6Gb/s and beyond, DDR3 has become the de facto mainstream memory technology especially for server and notebook applications in the 1H of 2010. Many other applications are available in the market today to take advantage of the superior performance features of DDR3 and DDR3L. Wintec currently offers following DDR3 and DDR3L Modules and will continue to add more solutions as DDR3/DDR3L enabled applications will proliferate.

### DDR3 240-Pin Unbuffered-ECC DIMMs

Standard Profile (1.181") with Nominal Voltage (1.5V)

Density	Part Number	Rank	DIMM Config	Component Config	Voltage
1GB	WD3UE01GX809-xxxxx-yy	1 rank	128x72	128Mx8	1.5V
2GB	WD3UE02GX818-xxxxx-yy	2 rank	256x72	128Mx8	1.5V
	WD3UE02GX809-xxxxx-yy	1 rank	256x72	256Mx8	1.5V
4GB	WD3UE04GX818-xxxxx-yy	2 rank	512x72	256Mx8	1.5V

Very Low Profile (0.72") with Nominal Voltage (1.5V)

Density	Part Number	Rank	DIMM Config	Component Config	Voltage
1GB	WD3UE01GX809V-xxxxx-yy	1 rank	128x72	128Mx8	1.5V
2GB	WD3UE02GX818V-xxxxx-yy	2 rank	256x72	128Mx8	1.5V

	WD3UE02GX809V-xxxxx-yy	1 rank	256x72	256Mx8	1.5V
4GB	WD3UE04GX818V-xxxxx-yy	2 rank	512x72	256Mx8	1.5V

## DDR3 240-Pin DIMM - Unbuffered Non-ECC

Standard Profile (1.181") with Nominal Voltage (1.5V)

Density	Part Number	Rank	DIMM Config	Component Config	Voltage
1GB	WD3UN01GX808-xxxxx-yy	1 rank	128x64	128Mx8	1.5V
2GB	WD3UN02GX816-xxxxx-yy	2 rank	256x64	128Mx8	1.5V
	WD3UN02GX808-xxxxx-yy	1 rank	256x64	256Mx8	1.5V
4GB	WD3UN04GX816-xxxxx-yy	2 rank	512x64	256Mx4	1.5V
8GB	WD3UN08GX816-xxxxx-yy	2 rank	1024x64	512Mx4	1.5V

(xxxxx) Module speed (MHz) and Cas Latency

= 1066J : 1066MHz CL 7  
1333L : 1333MHz CL9  
1600N :1600MHz CL11

DRAM Manufacturer and Die Revision

(yy) = P: Samsung           A: A-Die  
H: Micron                B: B-Die  
C: Hynix                 C: C-Die

Buffer / Register set (Only applies to Registered/Buffered modules)

(z) = I: Inphi  
D: IDT  
L: Intel